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PATENT APPLICATION

ATTORNEY DOCKET NO. 200312670-1

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Inventor(s): Neal W. Meyer et al

Confirmation No.: 2065

Application No.: 10/822064

Examiner: unassigned

Filing Date: Apr 08, 2004

Group Art Unit:

Title: Bonding An Interconnect To A Circuit Device And Related Devices

Mail Stop Amendment
Commissioner For Patents
PO Box 1450
Alexandria, VA 22313-1450

INFORMATION DISCLOSURE STATEMENT

This Information Disclosure Statement is submitted:

- ☒ under 37 CFR 1.97 (b), or
(Within three months of filing national application; or date of entry of national application; or before mailing date of first action on the merits; whichever occurs last)
- ☐ under 37 CFR 1.97 (c), together with either a:
☐ Statement under 37 CFR 1.97 (e), or
☐ a \$180 fee under 37 CFR 1.17 (p), or
 (After the CFR 1.97 (b) time period, but before final action or notice of allowance, whichever occurs first)
- ☐ under 37 CFR 1.97 (d), together with either a:
☐ Statement under 37 CFR 1.97 (e)(1) or (2), and
☐ a \$180 fee set forth in 37 CFR 1.17 (p)
 (Filed after final action, a notice of allowance, on or before payment of the issue fee)

Please charge to Deposit Account 08-2025 the sum of \$ 0.00 . At any time during the pendency of this application, please charge any fees required or credit any over payment to Deposit Account 08-2025 pursuant to 37 CFR 1.25.

Applicant(s) submit herewith form PTO 1449 - Information Disclosure Statement together with any required copies of patents, publications or other information of which applicant(s) are aware, which applicant(s) believe(s) may be material to the examination of this application and for which there may be a duty to disclose in accordance with 37 CFR 1.56.

- ☐ A concise explanation of the relevance of foreign language patents, foreign language publications and other foreign language information listed on PTO Form 1449, as presently understood by the individual(s) designated in 37 CFR 1.56 (c) most knowledgeable about the content is given on the attached sheet, or where a foreign language patent is cited in a search report or other action by a foreign patent office in a counterpart foreign application, an english language version of the search report or action which indicates the degree of relevance found by the foreign office is listed on form PTO 1449 and is enclosed.

It is requested that the information disclosed herein be made of record in this application.

- ☒ I hereby certify that this correspondence is being deposited with the United States Postal Service as first class mail in an envelope addressed to: Commissioner for Patents, Alexandria, VA 22313-1450

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Respectfully submitted,

Neal W. Meyer et al

By

Donald J. Coulman

Attorney/Agent for Applicant(s)

Reg No.: 50,406

Date: 1/5/06

Telephone: 541 715 1694

10822064 - GAU:

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Substitute for form 1449/PTO INFORMATION DISCLOSURE STATEMENT BY APPLICANT (Use as many sheets as necessary)		Complete if Known	
		Application Number	10/822064
		Filing Date	Apr 8, 2004
		First Named Inventor	Neal W. Meyer
		Art Unit	
		Examiner Name	unassigned
Sheet 2	of 2	Attorney Docket Number	200312670-1

NON PATENT LITERATURE DOCUMENTS			
Examiner Initials*	Cite No. ¹	Include name of the author (in CAPITAL LETTERS), title of the article (when appropriate), title of the item (book, magazine, journal, serial, symposium, catalog, etc.), date, page(s), volume-issue number(s), publisher, city and/or country where published.	T ²
/RC/		SHIGETOU, "Room temperature direct bonding of CMP-Cu film for bumpless interconnection", Electronic Components & Tech Conf, May 29, 2001, pgs 755-760.	
/RC/		SUGA, "Bump-less interconnect for next generation system packaging", Electronic Components & Tech Conf, May 29, 2001, pgs 1003-1008.	
/RC/		SUGA, "Surface activated bonding for new flip chip and bumpless interconnect systems", Electronic Components & Tech Conf, May 29, 2001, pgs 105-111.	

Examiner Signature	/Rick Chang/	Date Considered	11/25/2007
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*EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.

¹ Applicant's unique citation designation number (optional). ² Applicant is to place a check mark here if English language Translation is attached.

This collection of information is required by 37 CFR 1.98. The information is required to obtain or retain a benefit by the public which is to file (and by the USPTO to process) an application. Confidentiality is governed by 35 U.S.C. 122 and 37 CFR 1.14. This collection is estimated to take 2 hours to complete, including gathering, preparing, and submitting the completed application form to the USPTO. Time will vary depending upon the individual case. Any comments on the amount of time you require to complete this form and/or suggestions for reducing this burden, should be sent to the Chief Information Officer, U.S. Patent and Trademark Office, P.O. Box 1450, Alexandria, VA 22313-1450. DO NOT SEND FEES OR COMPLETED FORMS TO THIS ADDRESS. SEND TO: Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450.

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ALL REFERENCES CONSIDERED EXCEPT WHERE LINED THROUGH. /RC/